

Welcome to [E-XFL.COM](#)**Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)**

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

**Applications of Embedded - CPLDs****Details**

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	2.3V ~ 2.7V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4512b-5tn176i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4512b-5tn176i</a>

**Table 2. ispMACH 4000Z Family Selection Guide**

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t <sub>PD</sub> (ns)	3.5	3.7	4.2	4.5
t <sub>S</sub> (ns)	2.2	2.5	2.7	2.9
t <sub>CO</sub> (ns)	3.0	3.2	3.5	3.8
f <sub>MAX</sub> (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I <sub>cc</sub> ( $\mu$ A)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

## ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V<sub>CC</sub> (logic core).

## Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

**Table 7. ORP Combinations for I/O Blocks with 16 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

**Table 8. ORP Combinations for I/O Blocks with 4 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

**Table 9. ORP Combinations for I/O Blocks with 10 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

**Table 10. ORP Combinations for I/O Blocks with 12 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

### ORP Bypass and Fast Output Multiplexers

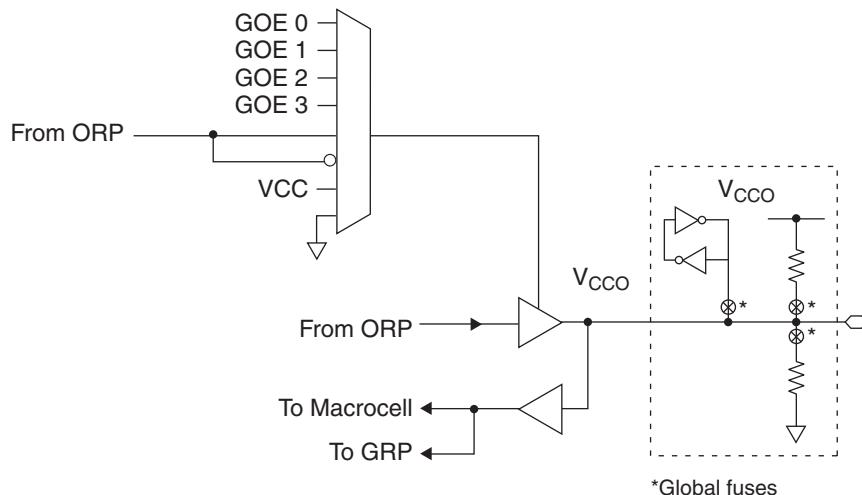
The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster  $t_{CO}$ .

### Output Enable Routing Multiplexers

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

### I/O Cell

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

**Figure 8. I/O Cell**

Each output supports a variety of output standards dependent on the  $V_{CCO}$  supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the  $V_{CCO}$  supplied to its I/O bank. The I/O standards supported are:

**Absolute Maximum Ratings<sup>1, 2, 3</sup>**

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage ( $V_{CC}$ ) . . . . .	-0.5 to 2.5V	-0.5 to 5.5V . . . . .	-0.5 to 5.5V
Output Supply Voltage ( $V_{CCO}$ ) . . . . .	-0.5 to 4.5V	-0.5 to 4.5V . . . . .	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied <sup>4, 5</sup> . . . . .	-0.5 to 5.5V	-0.5 to 5.5V . . . . .	-0.5 to 5.5V
Storage Temperature . . . . .	-65 to 150°C	-65 to 150°C . . . . .	-65 to 150°C
Junction Temperature ( $T_j$ ) with Power Applied . . . . .	-55 to 150°C	-55 to 150°C . . . . .	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of ( $V_{IH}$  (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with  $V_{IN} > 3.6V$  is allowed.

**Recommended Operating Conditions**

Symbol	Parameter	Min.	Max.	Units
$V_{CC}$	ispMACH 4000C	1.65	1.95	V
	ispMACH 4000Z	1.7	1.9	V
	ispMACH 4000Z, Extended Functional Voltage Operation	1.6 <sup>1, 2</sup>	1.9	V
	Supply Voltage for 2.5V Devices	2.3	2.7	V
$T_j$	Supply Voltage for 3.3V Devices	3.0	3.6	V
	Junction Temperature (Commercial)	0	90	C
	Junction Temperature (Industrial)	-40	105	C
	Junction Temperature (Extended)	-40	130	C

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

**Erase Reprogram Specifications**

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

**Hot Socketing Characteristics<sup>1, 2, 3</sup>**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{DK}$	Input or I/O Leakage Current	$0 \leq V_{IN} \leq 3.0V, T_j = 105^{\circ}C$	—	$\pm 30$	$\pm 150$	$\mu A$
		$0 \leq V_{IN} \leq 3.0V, T_j = 130^{\circ}C$	—	$\pm 30$	$\pm 200$	$\mu A$

1. In insensitive to sequence of  $V_{CC}$  or  $V_{CCO}$ . However, assumes monotonic rise/fall rates for  $V_{CC}$  and  $V_{CCO}$ , provided  $(V_{IN} - V_{CCO}) \leq 3.6V$ .
2.  $0 < V_{CC} < V_{CC}$  (MAX),  $0 < V_{CCO} < V_{CCO}$  (MAX).
3.  $I_{DK}$  is additive to  $I_{PU}$ ,  $I_{PD}$  or  $I_{BH}$ . Device defaults to pull-up until fuse circuitry is active.

**Supply Current, ispMACH 4000V/B/C****Over Recommended Operating Conditions**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4032V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	11.8	—	mA
		Vcc = 2.5V	—	11.8	—	mA
		Vcc = 1.8V	—	1.8	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.3	—	mA
		Vcc = 2.5V	—	11.3	—	mA
		Vcc = 1.8V	—	1.3	—	mA
<b>ispMACH 4064V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC <sup>5</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
<b>ispMACH 4128V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
<b>ispMACH 4256V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
<b>ispMACH 4384V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	13.5	—	mA
		Vcc = 2.5V	—	13.5	—	mA
		Vcc = 1.8V	—	3.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
<b>ispMACH 4512V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	14	—	mA
		Vcc = 2.5V	—	14	—	mA
		Vcc = 1.8V	—	4	—	mA

**ispMACH 4000V/B/C External Switching Characteristics (Cont.)****Over Recommended Operating Conditions**

Parameter	Description <sup>1, 2, 3</sup>	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t <sub>PD_MG</sub>	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t <sub>S</sub>	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t <sub>R</sub>	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t <sub>RW</sub>	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
t <sub>PTOE/DIS</sub>	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
t <sub>GPTOE/DIS</sub>	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
t <sub>GOE/DIS</sub>	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t <sub>CW</sub>	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1/ (t <sub>S</sub> + t <sub>CO</sub> )]	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

**ispMACH 4000V/B/C Internal Timing Parameters**

Over Recommended Operating Conditions

Parameter	Description	-2.5	-2.7	-3	-3.5	Units
<b>In/Out Delays</b>						
$t_{IN}$	Input Buffer Delay	—	0.60	—	0.60	—
$t_{GOE}$	Global OE Pin Delay	—	2.04	—	2.54	—
$t_{GCLK\_IN}$	Global Clock Input Buffer Delay	—	0.78	—	1.28	—
$t_{BUF}$	Delay through Output Buffer	—	0.85	—	0.85	—
$t_{EN}$	Output Enable Time	—	0.96	—	0.96	—
$t_{DIS}$	Output Disable Time	—	0.96	—	0.96	—
<b>Routing/GLB Delays</b>						
$t_{ROUTE}$	Delay through GRP	—	0.61	—	0.81	—
$t_{MCELL}$	Macrocell Delay	—	0.45	—	0.55	—
$t_{INREG}$	Input Buffer to Macrocell Register Delay	—	0.11	—	0.31	—
$t_{FBK}$	Internal Feedback Delay	—	0.00	—	0.00	—
$t_{PDb}$	5-PT Bypass Propagation Delay	—	0.44	—	0.44	—
$t_{PDi}$	Macrocell Propagation Delay	—	0.64	—	0.64	—
<b>Register/Latch Delays</b>						
$t_S$	D-Register Setup Time (Global Clock)	0.92	—	1.12	—	1.02
$t_{S\_PT}$	D-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
$t_{ST}$	T-Register Setup Time (Global Clock)	1.12	—	1.32	—	1.22
$t_{ST\_PT}$	T-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
$t_H$	D-Register Hold Time	0.88	—	0.68	—	0.98
$t_{HT}$	T-Register Hold Time	0.88	—	0.68	—	0.98
$t_{SIR}$	D-Input Register Setup Time (Global Clock)	0.82	—	1.37	—	1.27
$t_{SIR\_PT}$	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45
$t_{HIR}$	D-Input Register Hold Time (Global Clock)	0.88	—	0.63	—	0.73
$t_{HIR\_PT}$	D-Input Register Hold Time (Product Term Clock)	0.88	—	0.63	—	0.73
$t_{COi}$	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.52	—
$t_{CES}$	Clock Enable Setup Time	2.25	—	2.25	—	2.25
$t_{CEH}$	Clock Enable Hold Time	1.88	—	1.88	—	1.88
$t_{SL}$	Latch Setup Time (Global Clock)	0.92	—	1.12	—	1.02
$t_{SL\_PT}$	Latch Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
$t_{HL}$	Latch Hold Time	1.17	—	1.17	—	1.17
$t_{GOi}$	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—

**ispMACH 4000V/B/C Internal Timing Parameters**

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>In/Out Delays</b>								
$t_{IN}$	Input Buffer Delay	—	0.95	—	1.50	—	2.00	ns
$t_{GOE}$	Global OE Pin Delay	—	4.04	—	6.04	—	7.04	ns
$t_{GCLK\_IN}$	Global Clock Input Buffer Delay	—	1.83	—	2.28	—	3.28	ns
$t_{BUF}$	Delay through Output Buffer	—	1.00	—	1.50	—	1.50	ns
$t_{EN}$	Output Enable Time	—	0.96	—	0.96	—	0.96	ns
$t_{DIS}$	Output Disable Time	—	0.96	—	0.96	—	0.96	ns
<b>Routing/GLB Delays</b>								
$t_{ROUTE}$	Delay through GRP	—	1.51	—	2.26	—	3.26	ns
$t_{MCELL}$	Macrocell Delay	—	1.05	—	1.45	—	1.95	ns
$t_{INREG}$	Input Buffer to Macrocell Register Delay	—	0.56	—	0.96	—	1.46	ns
$t_{FBK}$	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	ns
$t_{PD_b}$	5-PT Bypass Propagation Delay	—	1.54	—	2.24	—	3.24	ns
$t_{PD_i}$	Macrocell Propagation Delay	—	0.94	—	1.24	—	1.74	ns
<b>Register/Latch Delays</b>								
$t_S$	D-Register Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
$t_{S\_PT}$	D-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
$t_{ST}$	T-Register Setup Time (Global Clock)	1.52	—	1.77	—	1.77	—	ns
$t_{ST\_PT}$	T-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
$t_H$	D-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
$t_{HT}$	T-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
$t_{SIR}$	D-Input Register Setup Time (Global Clock)	1.52	—	1.57	—	1.57	—	ns
$t_{SIR\_PT}$	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
$t_{HIR}$	D-Input Register Hold Time (Global Clock)	0.68	—	1.18	—	1.18	—	ns
$t_{HIR\_PT}$	D-Input Register Hold Time (Product Term Clock)	0.68	—	1.18	—	1.18	—	ns
$t_{COi}$	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.67	—	1.17	ns
$t_{CES}$	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	ns
$t_{CEH}$	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	ns
$t_{SL}$	Latch Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
$t_{SL\_PT}$	Latch Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
$t_{HL}$	Latch Hold Time	1.17	—	1.17	—	1.17	—	ns
$t_{GOi}$	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
$t_{PDLi}$	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
$t_{SRi}$	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	ns
$t_{SRR}$	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	ns
<b>Control Delays</b>								
$t_{BCLK}$	GLB PT Clock Delay	—	1.12	—	1.12	—	0.62	ns
$t_{PTCLK}$	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	ns
$t_{BSR}$	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
$t_{PTSR}$	Macrocell PT Set/Reset Delay	—	2.51	—	3.41	—	3.41	ns

**ispMACH 4000Z Internal Timing Parameters (Cont.)**

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>In/Out Delays</b>								
$t_{IN}$	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
$t_{GOE}$	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
$t_{GCLK\_IN}$	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
$t_{BUF}$	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
$t_{EN}$	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
$t_{DIS}$	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
<b>Routing/GLB Delays</b>								
$t_{ROUTE}$	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
$t_{MCELL}$	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
$t_{INREG}$	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
$t_{FBK}$	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
$t_{PD_b}$	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
$t_{PDI}$	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
<b>Register/Latch Delays</b>								
$t_S$	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
$t_{S\_PT}$	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
$t_{ST}$	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
$t_{ST\_PT}$	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
$t_H$	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
$t_{HT}$	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
$t_{SIR}$	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
$t_{SIR\_PT}$	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
$t_{HIR}$	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
$t_{HIR\_PT}$	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
$t_{COi}$	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
$t_{CES}$	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
$t_{CEH}$	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
$t_{SL}$	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
$t_{SL\_PT}$	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
$t_{HL}$	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
$t_{GOi}$	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
$t_{PDLi}$	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
$t_{SRi}$	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
$t_{SRR}$	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
<b>Control Delays</b>								
$t_{BCLK}$	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
$t_{PTCLK}$	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
$t_{BSR}$	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
$t_{PTSR}$	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
$t_{GPTOE}$	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

**ispMACH 4000Z Timing Adders<sup>1</sup>**

Adder Type	Base Parameter	Description	-35		-37		-42		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>									
t <sub>INDIO</sub>	t <sub>INREG</sub>	Input register delay	—	1.00	—	1.00	—	1.30	ns
t <sub>EXP</sub>	t <sub>MCELL</sub>	Product term expander delay	—	0.40	—	0.40	—	0.45	ns
t <sub>ORP</sub>	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t <sub>BLA</sub>	t <sub>ROUTE</sub>	Additional block loading adder	—	0.04	—	0.05	—	0.05	ns
<b>t<sub>IOI</sub> Input Adjusters</b>									
LVTTL_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
<b>t<sub>IOO</sub> Output Adjusters</b>									
LVTTL_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t <sub>BUF</sub> , t <sub>EN</sub>	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding the use of these adders.

**ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
62	1	E10	E^8
63	1	E12	E^9
64	1	E14	E^11
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F^0
69	1	F1	F^1
70	1	F2	F^2
71	1	F4	F^3
72	1	F5	F^4
73	1	F6	F^5
74	1	GND (Bank 1)	-
75	1	F8	F^6
76	1	F9	F^7
77	1	F10	F^8
78	1	F12	F^9
79	1	F13	F^10
80	1	F14	F^11
81	1	VCCO (Bank 1)	-
82	1	G14	G^11
83	1	G13	G^10
84	1	G12	G^9
85	1	G10	G^8
86	1	G9	G^7
87	1	G8	G^6
88	1	GND (Bank 1)	-
89	1	G6	G^5
90	1	G5	G^4
91	1	G4	G^3
92	1	G2	G^2
93	1	G0	G^0
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H^11
99	1	H13	H^10
100	1	H12	H^9
101	1	H10	H^8
102	1	H9	H^7
103	1	H8	H^6
104	1	GND (Bank 1)	-

**ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
105	1	VCCO (Bank 1)	-
106	1	H6	H^5
107	1	H5	H^4
108	1	H4	H^3
109	1	H2	H^2
110	1	H1	H^1
111	1	H0/GOE1	H^0
112	1	CLK3/I	-
113	0	GND (Bank 0)	-
114	0	CLK0/I	-
115	0	VCC	-
116	0	A0/GOE0	A^0
117	0	A1	A^1
118	0	A2	A^2
119	0	A4	A^3
120	0	A5	A^4
121	0	A6	A^5
122	0	VCCO (Bank 0)	-
123	0	GND (Bank 0)	-
124	0	A8	A^6
125	0	A9	A^7
126	0	A10	A^8
127	0	A12	A^9
128	0	A14	A^11

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:  
132-Ball csBGA**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	GND	-	GND	-	GND	-
B2	-	TDI	-	TDI	-	TDI	-
C1	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
C3	0	NC	-	B0	B^0	C12	C^6
C2	0	A8	A^8	B1	B^1	C10	C^5
D1	0	A9	A^9	B2	B^2	C8	C^4
D3	0	A10	A^10	B4	B^3	C6	C^3
D2	0	A11	A^11	B5	B^4	C4	C^2
E1	0	NC	-	B6	B^5	C2	C^1
E2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-

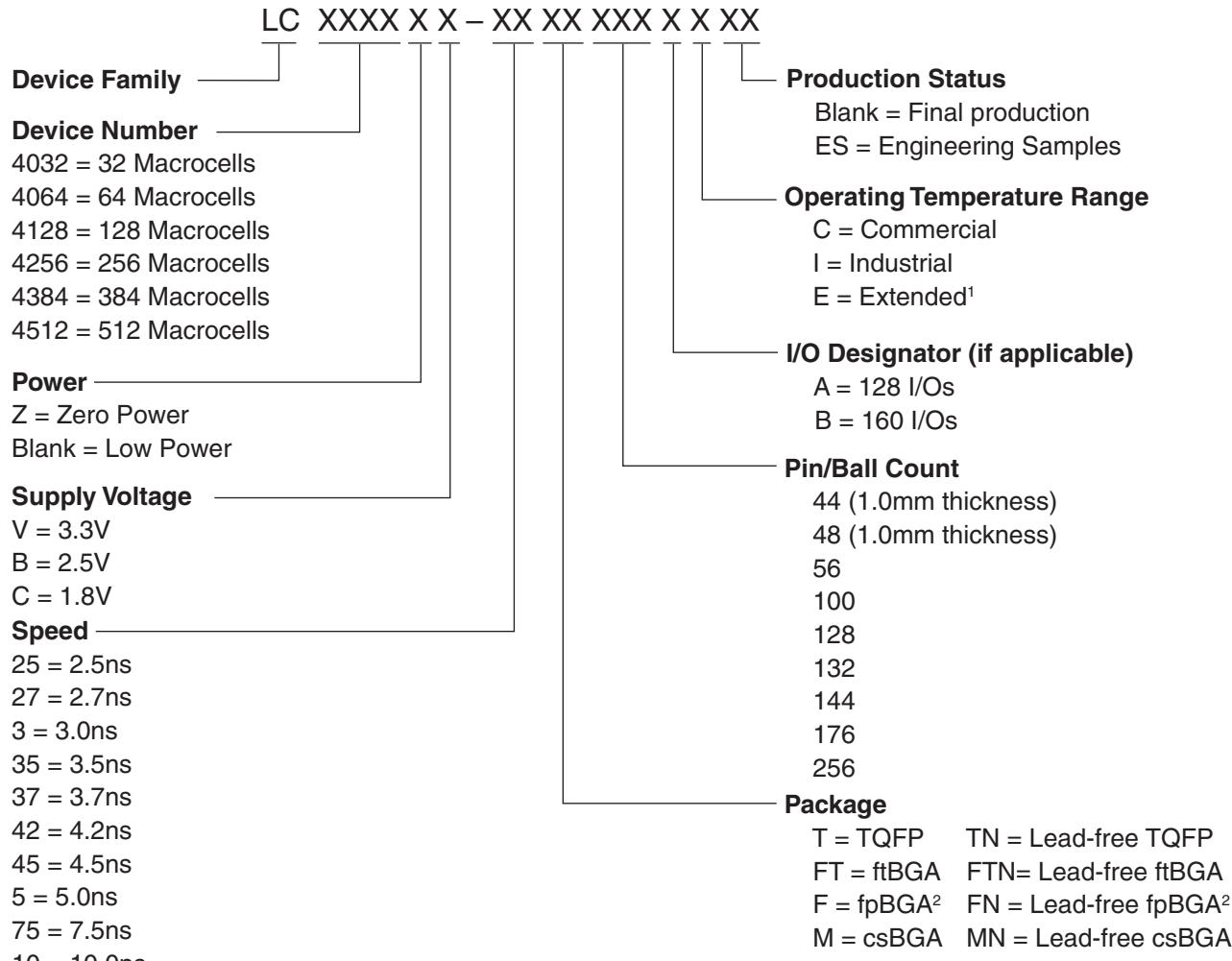
**ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
86	1	F12	F^9	L8	L^4
87	1	F13	F^10	L6	L^3
88	1	F14	F^11	L4	L^2
89	1	NC <sup>2</sup>	-	I <sup>2</sup>	-
90	1	GND (Bank 1) <sup>1</sup>	-	NC <sup>1</sup>	-
91	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
92	1	NC <sup>2</sup>	-	I <sup>2</sup>	-
93	1	G14	G^11	M2	M^1
94	1	G13	G^10	M4	M^2
95	1	G12	G^9	M6	M^3
96	1	G10	G^8	M8	M^4
97	1	G9	G^7	M10	M^5
98	1	G8	G^6	M12	M^6
99	1	GND (Bank 1)	-	GND (Bank 1)	-
100	1	G6	G^5	N2	N^1
101	1	G5	G^4	N4	N^2
102	1	G4	G^3	N6	N^3
103	1	G2	G^2	N8	N^4
104	1	G1	G^1	N10	N^5
105	1	G0	G^0	N12	N^6
106	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
107	-	TDO	-	TDO	-
108	-	VCC	-	VCC	-
109	-	GND	-	GND	-
110	1	NC <sup>2</sup>	-	I <sup>2</sup>	-
111	1	H14	H^11	O12	O^6
112	1	H13	H^10	O10	O^5
113	1	H12	H^9	O8	O^4
114	1	H10	H^8	O6	O^3
115	1	H9	H^7	O4	O^2
116	1	H8	H^6	O2	O^1
117	1	NC <sup>2</sup>	-	I <sup>2</sup>	-
118	1	GND (Bank 1)	-	GND (Bank 1)	-
119	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
120	1	H6	H^5	P12	P^6
121	1	H5	H^4	P10	P^5
122	1	H4	H^3	P8	P^4
123	1	H2	H^2	P6	P^3
124	1	H1	H^1	P4	P^2
125	1	H0 GOE1	H^0	P2 GOE1	P^1
126	1	CLK3/I	-	CLK3/I	-
127	0	GND (Bank 0)	-	GND (Bank 0)	-
128	0	CLK0/I	-	CLK0/I	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
C12	1	O0	O^0	O2	O^2	GX0	GX^0	OX0	OX^0
E10	1	NC	-	O1	O^1	CX8	CX^4	MX0	MX^0
A13	1	NC	-	O0	O^0	CX10	CX^5	MX4	MX^1
D12	1	NC	-	NC	-	NC	-	LX0	LX^0
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B12	1	NC	-	NC	-	NC	-	LX4	LX^1
A12	1	NC	-	NC	-	EX2	EX^1	LX8	LX^2
B11	1	NC	-	NC	-	EX0	EX^0	LX12	LX^3
A11	1	NC	-	P14	P^9	CX12	CX^6	MX8	MX^2
D10	1	NC	-	P12	P^8	CX14	CX^7	MX12	MX^3
C10	1	P14	P^7	P10	P^7	HX14	HX^7	PX14	PX^7
B10	1	P12	P^6	P9	P6	HX12	HX^6	PX12	PX^6
A10	1	P10	P^5	P8	P^5	HX10	HX^5	PX10	PX^5
A9	1	P8	P^4	P6	P^4	HX8	HX^4	PX8	PX^4
F9	1	P6	P^3	P4	P^3	HX6	HX^3	PX6	PX^3
B9	1	P4	P^2	P2	P^2	HX4	HX^2	PX4	PX^2
E9	1	P2/GOE1	P^1	P1/GOE1	P^1	HX2/GOE1	HX^1	PX2/GOE1	PX^1
C9	1	P0	P^0	P0	P^0	HX0	HX^0	PX0	PX^0
-	-	GND	-	GND	-	GND	-	GND	-
D9	1	CLK3/I	-	CLK3/I	-	CLK3/I	-	CLK3/I	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
B8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-	CLK0/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
D8	0	A0	A^0	A0	A^0	A0	A^0	A0	A^0
C8	0	A2/GOE0	A^1	A1/GOE0	A^1	A2/GOE0	A^1	A2/GOE0	A^1
A8	0	A4	A^2	A2	A^2	A4	A^2	A4	A^2
A7	0	A6	A^3	A4	A^3	A6	A^3	A6	A^3
B7	0	A8	A^4	A6	A^4	A8	A^4	A8	A^4
E8	0	A10	A^5	A8	A^5	A10	A^5	A10	A^5
D7	0	A12	A^6	A9	A^6	A12	A^6	A12	A^6
F8	0	A14	A^7	A10	A^7	A14	A^7	A14	A^7
C7	0	NC	-	A12	A^8	F14	F^7	D0	D^0
A6	0	NC	-	A14	A^9	F12	F^6	D4	D^1
B6	0	NC	-	NC	-	D14	D^7	E0	E^0
A5	0	NC	-	NC	-	D12	D^6	E4	E^1
B5	0	NC	-	NC	-	NC	-	E8	E^2
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
D5	0	NC	-	NC	-	NC	-	E12	E^3
A4	0	NC	-	B0	B^0	F10	F^5	D8	D^2

## Part Number Description



1. For automotive AEC-Q100 compliant devices, refer to the LA-ispmach 4000V/Z Automotive Family Data Sheet (DS1017).

2. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000 Family Speed Grade Offering

	-25	-27	-3	-35	-37	-42	-45	-5		-75			-10
	Com	Ind	Com	Ind	Ext	Ind							
ispMACH 4032V/B/C													1
ispMACH 4064V/B/C													1
ispMACH 4128V/B/C													1
ispMACH 4256V/B/C													
ispMACH 4384V/B/C													
ispMACH 4512V/B/C													
ispMACH 4032ZC													1
ispMACH 4064ZC													1
ispMACH 4128ZC													1
ispMACH 4256ZC													

1. 3.3V only.

## ispMACH 4000C (1.8V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4128C	LC4128C-27T128C	128	1.8	2.7	TQFP	128	92	C
	LC4128C-5T128C	128	1.8	5	TQFP	128	92	C
	LC4128C-75T128C	128	1.8	7.5	TQFP	128	92	C
	LC4128C-27T100C	128	1.8	2.7	TQFP	100	64	C
	LC4128C-5T100C	128	1.8	5	TQFP	100	64	C
	LC4128C-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256C	LC4256C-3FT256AC	256	1.8	3	ftBGA	256	128	C
	LC4256C-5FT256AC	256	1.8	5	ftBGA	256	128	C
	LC4256C-75FT256AC	256	1.8	7.5	ftBGA	256	128	C
	LC4256C-3FT256BC	256	1.8	3	ftBGA	256	160	C
	LC4256C-5FT256BC	256	1.8	5	ftBGA	256	160	C
	LC4256C-75FT256BC	256	1.8	7.5	ftBGA	256	160	C
	LC4256C-3F256AC <sup>1</sup>	256	1.8	3	fpBGA	256	128	C
	LC4256C-5F256AC <sup>1</sup>	256	1.8	5	fpBGA	256	128	C
	LC4256C-75F256AC <sup>1</sup>	256	1.8	7.5	fpBGA	256	128	C
	LC4256C-3F256BC <sup>1</sup>	256	1.8	3	fpBGA	256	160	C
	LC4256C-5F256BC <sup>1</sup>	256	1.8	5	fpBGA	256	160	C
	LC4256C-75F256BC <sup>1</sup>	256	1.8	7.5	fpBGA	256	160	C
	LC4256C-3T176C	256	1.8	3	TQFP	176	128	C
	LC4256C-5T176C	256	1.8	5	TQFP	176	128	C
	LC4256C-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256C-3T100C	256	1.8	3	TQFP	100	64	C
	LC4256C-5T100C	256	1.8	5	TQFP	100	64	C
	LC4256C-75T100C	256	1.8	7.5	TQFP	100	64	C
LC4384C	LC4384C-35FT256C	384	1.8	3.5	ftBGA	256	192	C
	LC4384C-5FT256C	384	1.8	5	ftBGA	256	192	C
	LC4384C-75FT256C	384	1.8	7.5	ftBGA	256	192	C
	LC4384C-35F256C <sup>1</sup>	384	1.8	3.5	fpBGA	256	192	C
	LC4384C-5F256C <sup>1</sup>	384	1.8	5	fpBGA	256	192	C
	LC4384C-75F256C <sup>1</sup>	384	1.8	7.5	fpBGA	256	192	C
	LC4384C-35T176C	384	1.8	3.5	TQFP	176	128	C
	LC4384C-5T176C	384	1.8	5	TQFP	176	128	C
	LC4384C-75T176C	384	1.8	7.5	TQFP	176	128	C
LC4512C	LC4512C-35FT256C	512	1.8	3.5	ftBGA	256	208	C
	LC4512C-5FT256C	512	1.8	5	ftBGA	256	208	C
	LC4512C-75FT256C	512	1.8	7.5	ftBGA	256	208	C
	LC4512C-35F256C <sup>1</sup>	512	1.8	3.5	fpBGA	256	208	C
	LC4512C-5F256C <sup>1</sup>	512	1.8	5	fpBGA	256	208	C
	LC4512C-75F256C <sup>1</sup>	512	1.8	7.5	fpBGA	256	208	C
	LC4512C-35T176C	512	1.8	3.5	TQFP	176	128	C
	LC4512C-5T176C	512	1.8	5	TQFP	176	128	C
	LC4512C-75T176C	512	1.8	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000B (2.5V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25TN48C	32	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4032B-5TN48C	32	2.5	5	Lead-Free TQFP	48	32	C
	LC4032B-75TN48C	32	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4032B-25TN44C	32	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4032B-5TN44C	32	2.5	5	Lead-Free TQFP	44	30	C
	LC4032B-75TN44C	32	2.5	7.5	Lead-Free TQFP	44	30	C
LC4064B	LC4064B-25TN100C	64	2.5	2.5	Lead-Free TQFP	100	64	C
	LC4064B-5TN100C	64	2.5	5	Lead-Free TQFP	100	64	C
	LC4064B-75TN100C	64	2.5	7.5	Lead-Free TQFP	100	64	C
	LC4064B-25TN48C	64	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4064B-5TN48C	64	2.5	5	Lead-Free TQFP	48	32	C
	LC4064B-75TN48C	64	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4064B-25TN44C	64	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4064B-5TN44C	64	2.5	5	Lead-Free TQFP	44	30	C
	LC4064B-75TN44C	64	2.5	7.5	Lead-Free TQFP	44	30	C
LC4128B	LC4128B-27TN128C	128	2.5	2.7	Lead-Free TQFP	128	92	C
	LC4128B-5TN128C	128	2.5	5	Lead-Free TQFP	128	92	C
	LC4128B-75TN128C	128	2.5	7.5	Lead-Free TQFP	128	92	C
	LC4128B-27TN100C	128	2.5	2.7	Lead-Free TQFP	100	92	C
	LC4128B-5TN100C	128	2.5	5	Lead-Free TQFP	100	92	C
	LC4128B-75TN100C	128	2.5	7.5	Lead-Free TQFP	100	92	C
LC4256B	LC4256B-3FTN256AC	256	2.5	3	Lead-Free ftBGA	256	128	C
	LC4256B-5FTN256AC	256	2.5	5	Lead-Free ftBGA	256	128	C
	LC4256B-75FTN256AC	256	2.5	7.5	Lead-Free ftBGA	256	128	C
	LC4256B-3FTN256BC	256	2.5	3	Lead-Free ftBGA	256	160	C
	LC4256B-5FTN256BC	256	2.5	5	Lead-Free ftBGA	256	160	C
	LC4256B-75FTN256BC	256	2.5	7.5	Lead-Free ftBGA	256	160	C
	LC4256B-3FN256AC <sup>1</sup>	256	2.5	3	Lead-Free fpBGA	256	128	C
	LC4256B-5FN256AC <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	128	C
	LC4256B-75FN256AC <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	128	C
	LC4256B-3FN256BC <sup>1</sup>	256	2.5	3	Lead-Free fpBGA	256	160	C
	LC4256B-5FN256BC <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	160	C
	LC4256B-75FN256BC <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	160	C
	LC4256B-3TN176C	256	2.5	3	Lead-Free TQFP	176	128	C
	LC4256B-5TN176C	256	2.5	5	Lead-Free TQFP	176	128	C
	LC4256B-75TN176C	256	2.5	7.5	Lead-Free TQFP	176	128	C
	LC4256B-3TN100C	256	2.5	3	Lead-Free TQFP	100	64	C
	LC4256B-5TN100C	256	2.5	5	Lead-Free TQFP	100	64	C
	LC4256B-75TN100C	256	2.5	7.5	Lead-Free TQFP	100	64	C

## ispMACH 4000B (2.5V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4128B	LC4128B-5TN128I	128	2.5	5	Lead-Free TQFP	128	92	I
	LC4128B-75TN128I	128	2.5	7.5	Lead-Free TQFP	128	92	I
	LC4128B-10TN128I	128	2.5	10	Lead-Free TQFP	128	92	I
	LC4128B-5TN100I	128	2.5	5	Lead-Free TQFP	100	64	I
	LC4128B-75TN100I	128	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4128B-10TN100I	128	2.5	10	Lead-Free TQFP	100	64	I
LC4256B	LC4256B-5FTN256AI	256	2.5	5	Lead-Free ftBGA	256	128	I
	LC4256B-75FTN256AI	256	2.5	7.5	Lead-Free ftBGA	256	128	I
	LC4256B-10FTN256AI	256	2.5	10	Lead-Free ftBGA	256	128	I
	LC4256B-5FTN256BI	256	2.5	5	Lead-Free ftBGA	256	160	I
	LC4256B-75FTN256BI	256	2.5	7.5	Lead-Free ftBGA	256	160	I
	LC4256B-10FTN256BI	256	2.5	10	Lead-Free ftBGA	256	160	I
	LC4256B-5FN256AI <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	128	I
	LC4256B-75FN256AI <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	128	I
	LC4256B-10FN256AI <sup>1</sup>	256	2.5	10	Lead-Free fpBGA	256	128	I
	LC4256B-5FN256BI <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	160	I
	LC4256B-75FN256BI <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	160	I
	LC4256B-10FN256BI <sup>1</sup>	256	2.5	10	Lead-Free fpBGA	256	160	I
	LC4256B-5TN176I	256	2.5	5	Lead-Free TQFP	176	128	I
	LC4256B-75TN176I	256	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4256B-10TN176I	256	2.5	10	Lead-Free TQFP	176	128	I
	LC4256B-5TN100I	256	2.5	5	Lead-Free TQFP	100	64	I
	LC4256B-75TN100I	256	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4256B-10TN100I	256	2.5	10	Lead-Free TQFP	100	64	I
LC4384B	LC4384B-5FTN256I	384	2.5	5	Lead-Free ftBGA	256	192	I
	LC4384B-75FTN256I	384	2.5	7.5	Lead-Free ftBGA	256	192	I
	LC4384B-10FTN256I	384	2.5	10	Lead-Free ftBGA	256	192	I
	LC4384B-5FN256I <sup>1</sup>	384	2.5	5	Lead-Free fpBGA	256	192	I
	LC4384B-75FN256I <sup>1</sup>	384	2.5	7.5	Lead-Free fpBGA	256	192	I
	LC4384B-10FN256I <sup>1</sup>	384	2.5	10	Lead-Free fpBGA	256	192	I
	LC4384B-5TN176I	384	2.5	5	Lead-Free TQFP	176	128	I
	LC4384B-75TN176I	384	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4384B-10TN176I	384	2.5	10	Lead-Free TQFP	176	128	I
LC4512B	LC4512B-5FTN256I	512	2.5	5	Lead-Free ftBGA	256	208	I
	LC4512B-75FTN256I	512	2.5	7.5	Lead-Free ftBGA	256	208	I
	LC4512B-10FTN256I	512	2.5	10	Lead-Free ftBGA	256	208	I
	LC4512B-5FN256I <sup>1</sup>	512	2.5	5	Lead-Free fpBGA	256	208	I
	LC4512B-75FN256I <sup>1</sup>	512	2.5	7.5	Lead-Free fpBGA	256	208	I
	LC4512B-10FN256I <sup>1</sup>	512	2.5	10	Lead-Free fpBGA	256	208	I
	LC4512B-5TN176I	512	2.5	5	Lead-Free TQFP	176	128	I
	LC4512B-75TN176I	512	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4512B-10TN176I	512	2.5	10	Lead-Free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25TN48C	32	3.3	2.5	Lead-free TQFP	48	32	C
	LC4032V-5TN48C	32	3.3	5	Lead-free TQFP	48	32	C
	LC4032V-75TN48C	32	3.3	7.5	Lead-free TQFP	48	32	C
	LC4032V-25TN44C	32	3.3	2.5	Lead-free TQFP	44	30	C
	LC4032V-5TN44C	32	3.3	5	Lead-free TQFP	44	30	C
	LC4032V-75TN44C	32	3.3	7.5	Lead-free TQFP	44	30	C
LC4064V	LC4064V-25TN100C	64	3.3	2.5	Lead-free TQFP	100	64	C
	LC4064V-5TN100C	64	3.3	5	Lead-free TQFP	100	64	C
	LC4064V-75TN100C	64	3.3	7.5	Lead-free TQFP	100	64	C
	LC4064V-25TN48C	64	3.3	2.5	Lead-free TQFP	48	32	C
	LC4064V-5TN48C	64	3.3	5	Lead-free TQFP	48	32	C
	LC4064V-75TN48C	64	3.3	7.5	Lead-free TQFP	48	32	C
	LC4064V-25TN44C	64	3.3	2.5	Lead-free TQFP	44	30	C
	LC4064V-5TN44C	64	3.3	5	Lead-free TQFP	44	30	C
	LC4064V-75TN44C	64	3.3	7.5	Lead-free TQFP	44	30	C
LC4128V	LC4128V-27TN144C	128	3.3	2.7	Lead-free TQFP	144	96	C
	LC4128V-5TN144C	128	3.3	5	Lead-free TQFP	144	96	C
	LC4128V-75TN144C	128	3.3	7.5	Lead-free TQFP	144	96	C
	LC4128V-27TN128C	128	3.3	2.7	Lead-free TQFP	128	92	C
	LC4128V-5TN128C	128	3.3	5	Lead-free TQFP	128	92	C
	LC4128V-75TN128C	128	3.3	7.5	Lead-free TQFP	128	92	C
	LC4128V-27TN100C	128	3.3	2.7	Lead-free TQFP	100	64	C
	LC4128V-5TN100C	128	3.3	5	Lead-free TQFP	100	64	C
	LC4128V-75TN100C	128	3.3	7.5	Lead-free TQFP	100	64	C

## ispMACH 4000V (3.3V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5TN48I	32	3.3	5	Lead-free TQFP	48	32	I
	LC4032V-75TN48I	32	3.3	7.5	Lead-free TQFP	48	32	I
	LC4032V-10TN48I	32	3.3	10	Lead-free TQFP	48	32	I
	LC4032V-5TN44I	32	3.3	5	Lead-free TQFP	44	30	I
	LC4032V-75TN44I	32	3.3	7.5	Lead-free TQFP	44	30	I
	LC4032V-10TN44I	32	3.3	10	Lead-free TQFP	44	30	I
LC4064V	LC4064V-5TN100I	64	3.3	5	Lead-free TQFP	100	64	I
	LC4064V-75TN100I	64	3.3	7.5	Lead-free TQFP	100	64	I
	LC4064V-10TN100I	64	3.3	10	Lead-free TQFP	100	64	I
	LC4064V-5TN48I	64	3.3	5	Lead-free TQFP	48	32	I
	LC4064V-75TN48I	64	3.3	7.5	Lead-free TQFP	48	32	I
	LC4064V-10TN48I	64	3.3	10	Lead-free TQFP	48	32	I
	LC4064V-5TN44I	64	3.3	5	Lead-free TQFP	44	30	I
	LC4064V-75TN44I	64	3.3	7.5	Lead-free TQFP	44	30	I
	LC4064V-10TN44I	64	3.3	10	Lead-free TQFP	44	30	I
LC4128V	LC4128V-5TN144I	128	3.3	5	Lead-free TQFP	144	96	I
	LC4128V-75TN144I	128	3.3	7.5	Lead-free TQFP	144	96	I
	LC4128V-10TN144I	128	3.3	10	Lead-free TQFP	144	96	I
	LC4128V-5TN128I	128	3.3	5	Lead-free TQFP	128	92	I
	LC4128V-75TN128I	128	3.3	7.5	Lead-free TQFP	128	92	I
	LC4128V-10TN128I	128	3.3	10	Lead-free TQFP	128	92	I
	LC4128V-5TN100I	128	3.3	5	Lead-free TQFP	100	64	I
	LC4128V-75TN100I	128	3.3	7.5	Lead-free TQFP	100	64	I
	LC4128V-10TN100I	128	3.3	10	Lead-free TQFP	100	64	I